

ABSTRACT OF THE DISCLOSURE

A semiconductor integrated circuit device which requires high packaging density adopts a method for forming
5 bumps in a terminal section of a semiconductor chip and bonding
the semiconductor chip directly on a substrate. In this case,
in order to prevent damage to the semiconductor integrated
chip, which would otherwise be caused by bonding pressure
employed at the time of bonding operation, non-connected dummy
10 bumps are provided at corner sections of the semiconductor
chip. Even when the dummy bumps are provided, there arises
a necessity for preventing an increase in the size of the
semiconductor chips, which would otherwise arise when the dummy
bumps are provided on the chip.